

WHAT IS CLAIMED IS:

1. A heat dissipation method for an electronic apparatus comprising a housing, and a circuit board mounted in the housing, the heat dissipation method comprising the steps of:

step 1: providing a heatsink plate having a bottom face rested on a surface of the housing; and

step 2: providing a heat conductive plate having a bottom face rested on a top face of the heatsink plate and a top face rested on a bottom face of the circuit board.

2. The heat dissipation method in accordance with claim 1, wherein the heat conductive plate is made of a heat conductive rubber.

3. The heat dissipation method in accordance with claim 1, wherein the heat conductive plate is made of a heat conductive soft pad.

4. The heat dissipation method in accordance with claim 1, wherein each of the housing and the heatsink plate is made of silver.

5. The heat dissipation method in accordance with claim 1, wherein each of the housing and the heatsink plate is made of aluminum.

6. The heat dissipation method in accordance with claim 1, wherein each of the housing and the heatsink plate is made of copper.

7. The heat dissipation method in accordance with claim 1, further comprising the step of providing a heatsink material coated between the surface of the housing and the bottom face of the heatsink plate.

1 8. The heat dissipation method in accordance with claim 7, wherein
2 the heatsink material is a heatsink paste.

3 9. The heat dissipation method in accordance with claim 1, further
4 comprising the step of providing a heatsink material coated between the top
5 face of the heatsink plate and the bottom face of the heat conductive plate.

6 10. The heat dissipation method in accordance with claim 9, wherein
7 the heatsink material is a heatsink paste.

8 11. An electronic apparatus comprising:

9 a housing;

10 a circuit board mounted in the housing; and

11 a heatsink device mounted between and rested on the housing and the
12 circuit board.

13 12. The electronic apparatus in accordance with claim 11, wherein
14 the heatsink device includes a heatsink plate having a bottom face rested on a
15 surface of the housing, and a heat conductive plate having a bottom face rested
16 on a top face of the heatsink plate and a top face rested on a bottom face of the
17 circuit board.

18 13. The electronic apparatus in accordance with claim 12, wherein
19 the heatsink device further includes a heatsink material coated between the
20 surface of the housing and the bottom face of the heatsink plate.

21 14. The electronic apparatus in accordance with claim 13, wherein
22 the heatsink material is a heatsink paste.

1 15. The electronic apparatus in accordance with claim 12, wherein
2 the heatsink device further includes a heatsink material coated between the top
3 face of the heatsink plate and the bottom face of the heat conductive plate.

4 16. The electronic apparatus in accordance with claim 15, wherein
5 the heatsink material is a heatsink paste.

6 17. The electronic apparatus in accordance with claim 12, wherein
7 the heat conductive plate is made of a heat conductive rubber or soft pad.

8 18. The electronic apparatus in accordance with claim 12, wherein
9 each of the housing and the heatsink plate is made of silver.

10 19. The electronic apparatus in accordance with claim 12, wherein
11 each of the housing and the heatsink plate is made of aluminum.

12 20. The electronic apparatus in accordance with claim 12, wherein
13 each of the housing and the heatsink plate is made of copper.